

10 9 8 7 6 5 4 3 2 1

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F

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C

B

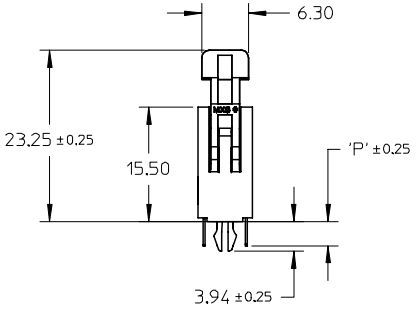
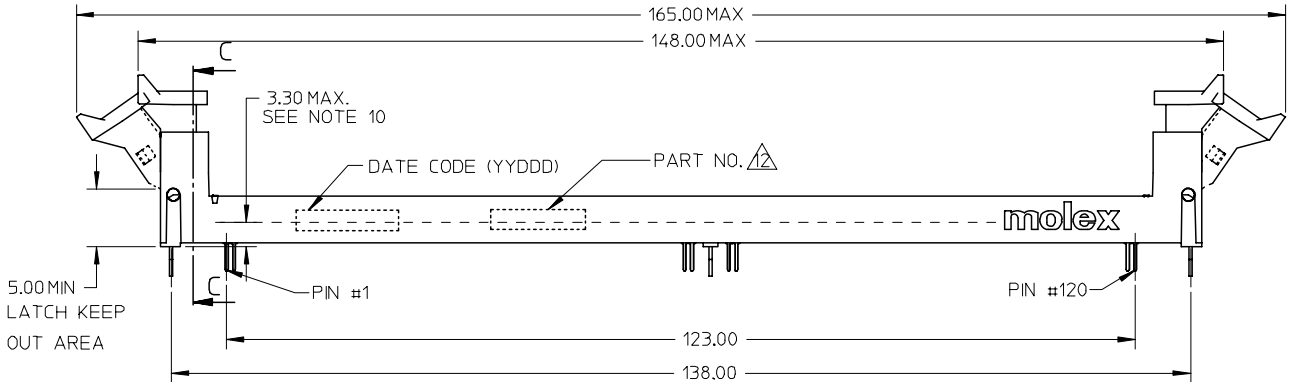
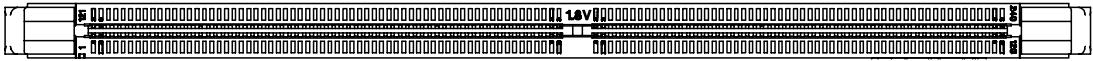
B

A

A

NOTES:

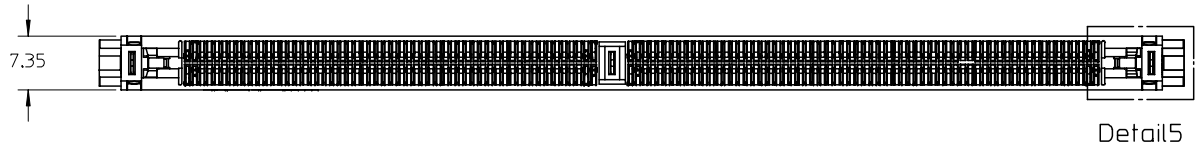
1. MATERIALS
 HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
 COLOR: BLACK
 EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
 COLOR: SEE TABLE
 TERMINAL - COPPER ALLOY
 2. PLATING - SEE TABLE IN SHEET 5 & 6.
 3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.
 (MEASURED OVER P.C. PADS)
 4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.
 5. REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE SPECIFICATIONS.
 6. PRODUCT SHALL BE PACKED IN TRAY.
 7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
 8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.
 9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.
 10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.
 11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.
- △ PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-****



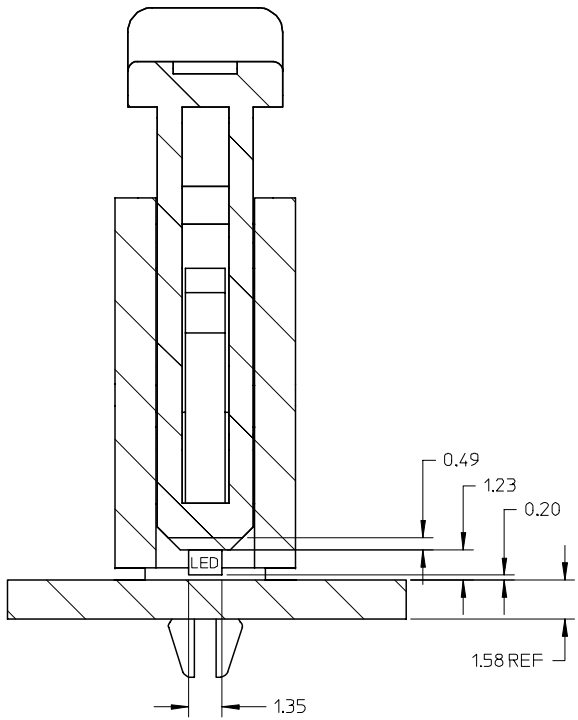
EC NO: S2006-0545 DRWN: KYTANG 2005/11/24 CHKD: SRAMESH 2005/11/24 APPR: GGLEE 2005/11/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
			mm	INCH	DRAWN BY	DATE	TITLE	
		4 PLACES	± ---	± ---	CG0H	2002/05/09	DDR2 DIMM, 1MM PITCH	
3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS			
2 PLACES	± 0.20	± ---	DS0H	2002/07/22	(FORKLOCK VERSION)			
1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED			
		ANGULAR ± 5 °	SKT0H	2002/07/23				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	SEE TABLE	DOCUMENT NO.	SHEET NO.		
			SIZE	A3	SD-87705-001	1 OF 6		

9 8 7 6 5 4 3 2 1

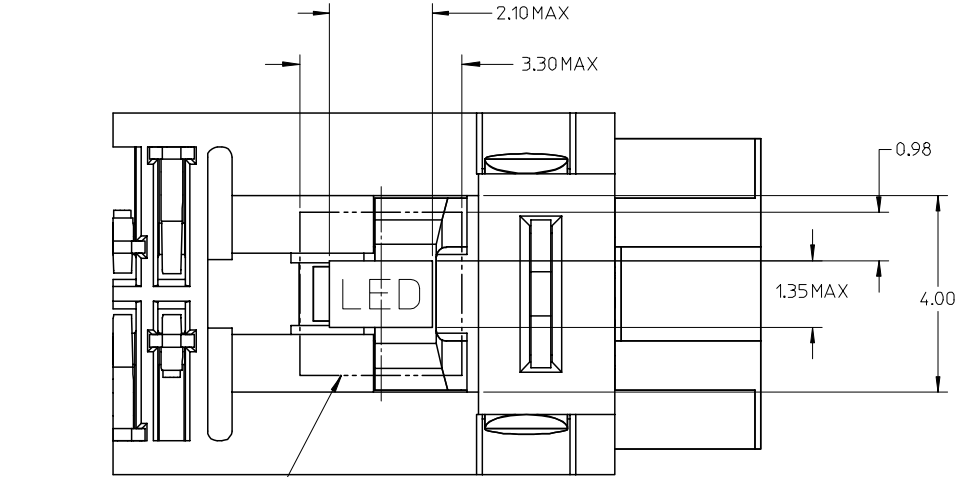
10 9 8 7 6 5 4 3 2 1



Detail5



SECTION C-C



LED PLACEMENT AREA

Detail5

EC NO: S2006-0545 2005/11/24 DRWN: KYTANG 2005/11/24 CHKD: SRAMESH 2005/11/25 APPR: GGLEE	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CG0H	DATE 2002/05/09	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS (FORKLOCK VERSION)				
		3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	CHECKED BY DS0H	DATE 2002/07/22	MOLEX INCORPORATED				
		1 PLACE ± --- ± ---	ANGULAR ± 5 °	APPROVED BY SKT0H	DATE 2002/07/23	DOCUMENT NO. SD-87705-001	SHEET NO. 2 OF 6			
C5	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

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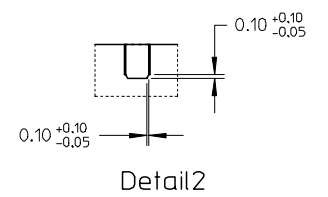
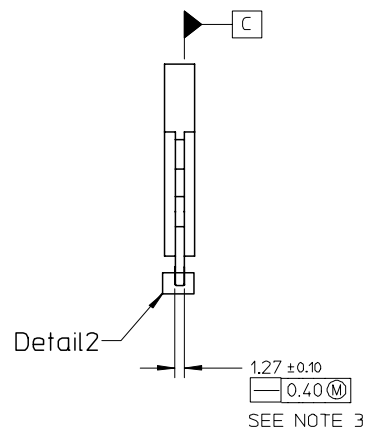
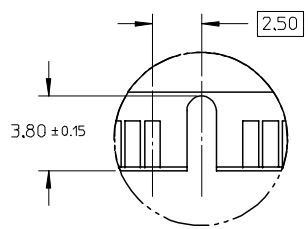
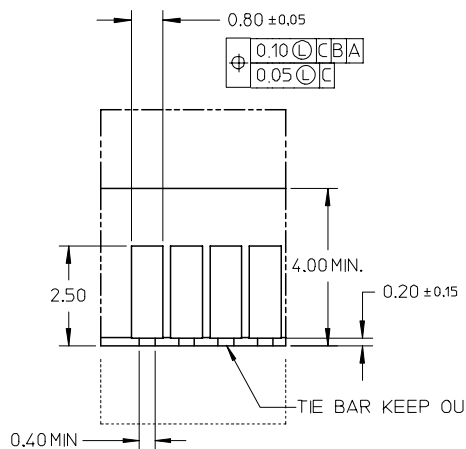
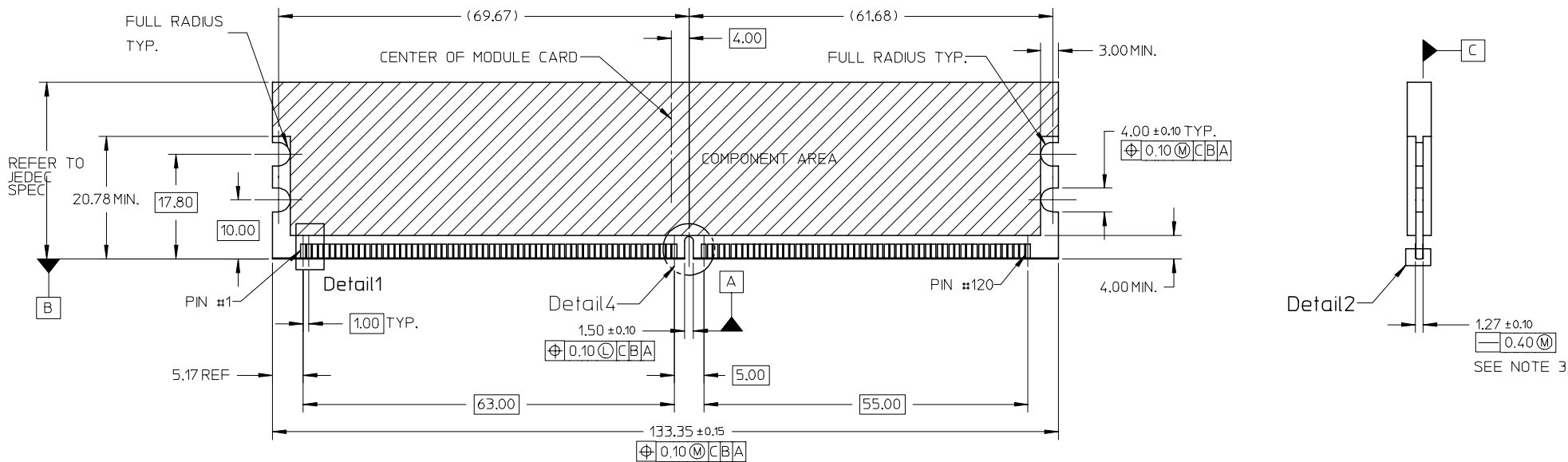
D D

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A A

RECOMMENDED MODULE LAYOUT



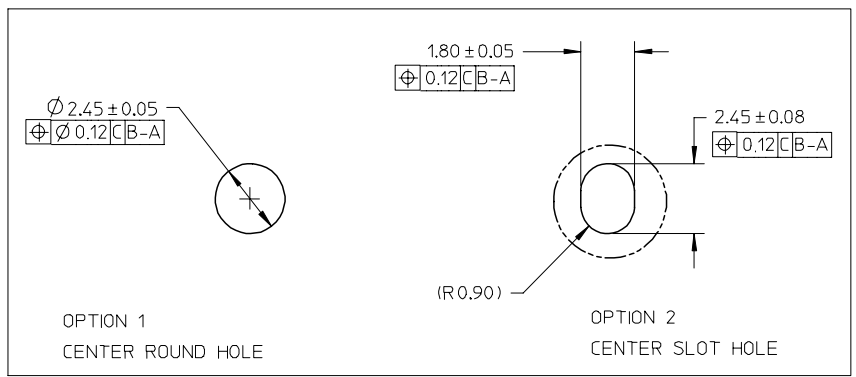
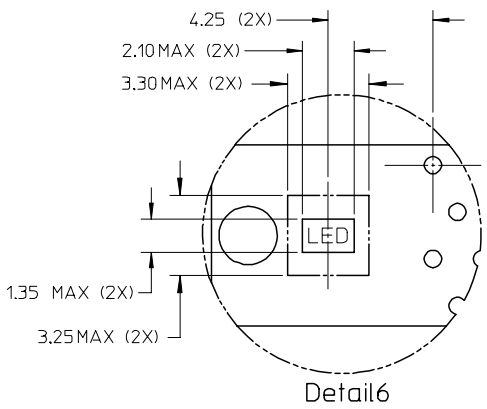
NOTES:
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

EC NO: S2006-0545 2005/11/24 DRWN: KYTANG CHKD: SRAMESH 2005/11/24 APPR: GGLEE 2005/11/25	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ∇=0	mm INCH	MM ONLY	NTS	METRIC		
		4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE			
		3 PLACES ± --- ± ---	CG0H 2002/05/09	DDR2 DIMM, 1MM PITCH			
		2 PLACES ± 0.20 ± ---	CHECKED BY DATE	240 CKTS			
	1 PLACE ± --- ± ---	DS0H 2002/07/22	(FORKLOCK VERSION)				
	ANGULAR ± 5 °	APPROVED BY DATE	MOLEX INCORPORATED				
		SKT0H 2002/07/23	MOLEX INCORPORATED				
		MATERIAL NO.	DOCUMENT NO.		SHEET NO.		
			SD-87705-001		3 OF 6		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

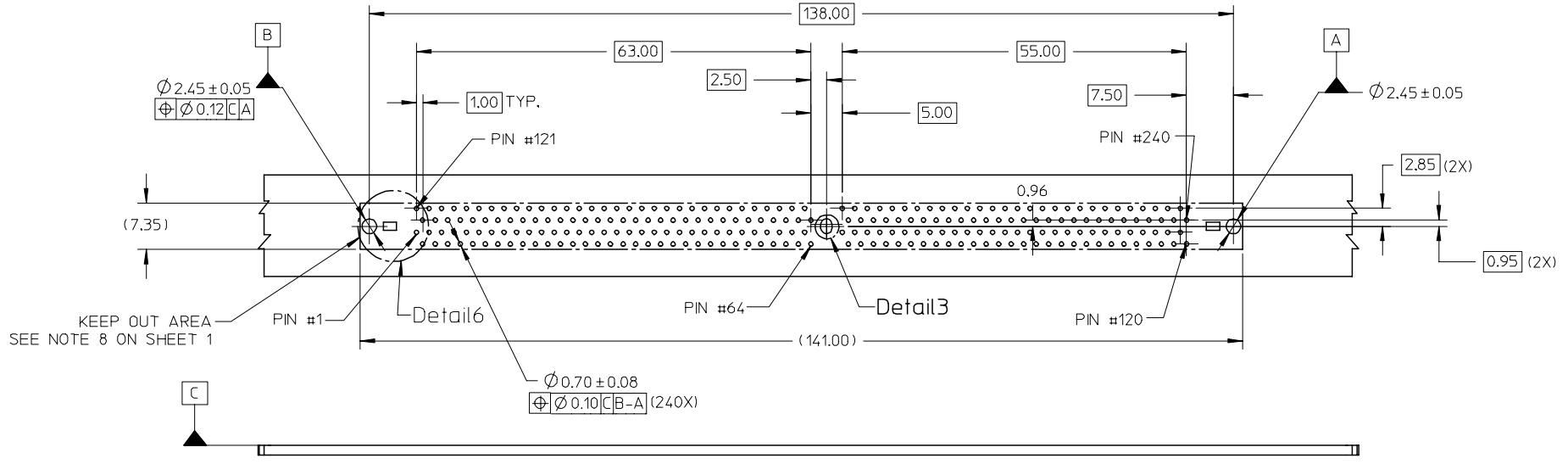
10 9 8 7 6 5 4 3 2 1

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(SEE RECOMMENDED THICKNESS IN TABLE)
RECOMMENDED PCB LAYOUT
CONNECTOR SIDE

Detail 3



EC NO: S2006-0545 2005/11/24 DRWN: KYTANG 2005/11/24 CHKD: SRAMESH 2005/11/24 APPR: GGLEE 2005/11/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS (FORKLOCK VERSION)		
							CHECKED BY DS0H	DATE 2002/07/22	MOLEX INCORPORATED		
							APPROVED BY SKTOH	DATE 2002/07/23	MOLEX INCORPORATED		
							MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87705-001	SHEET NO. 4 OF 6		

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-0001	CENTER (1.8V)	2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN/LEAD ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	NATURAL
87705-1001		3.18	2.36		
87705-0011		2.67	1.57	0.03µM / 1 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN/LEAD ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1011		3.18	2.36		
87705-0041		2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN/LEAD ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1041		3.18	2.36		
87705-0021		2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1021		3.18	2.36		
87705-1053		3.66			
87705-0031		2.67	1.57	0.03µM / 1 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1031		3.18	2.36		
87705-0051		2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1051		3.18	2.36		

EC NO: S2006-0545 DRWN: KYTANG 2005/11/24 CHKD: SRAMESH 2005/11/24 APPR: GGLEE 2005/11/25 C5	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table> ANGULAR ± 5 °		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY DRAWN BY CG0H DATE 2002/05/09 CHECKED BY DS0H DATE 2002/07/22 APPROVED BY SKT0H DATE 2002/07/23	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS (FORKLOCK VERSION)
		mm	INCH																	
	4 PLACES	± ---	± ---																	
	3 PLACES	± ---	± ---																	
2 PLACES	± 0.20	± ---																		
1 PLACE	± ---	± ---																		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE SIZE A3	MOLEX INCORPORATED	SHEET NO. 5 OF 6															
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	
				DOCUMENT NO. SD-87705-001																

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR	
87705-5041	CENTER (1.8V)	2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN/LEAD ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	CLEAR	
87705-5141		3.18	2.36			
87705-5051		2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE		
87705-5151		3.18	2.36			
87705-6151		3.18	2.36	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE		
87705-9001		2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN/LEAD ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE		BLACK
87705-9101		2.67	1.57			

EC NO: S2006-0545 2005/11/24 DRWN:KYTANG 2005/11/24 CHKD:SRAMESH 2005/11/25 APPR:GJLEE 2005/11/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS (FORKLOCK VERSION)			
		4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2002/07/22				
		3 PLACES	± ---	± ---	APPROVED BY SKTOH		DATE 2002/07/23	MOLEX INCORPORATED DOCUMENT NO. SD-87705-001 SHEET NO. 6 OF 6		
2 PLACES	± 0.20	± ---	MATERIAL NO.		DATE					
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
C5		REV								

9 8 7 6 5 4 3 2 1